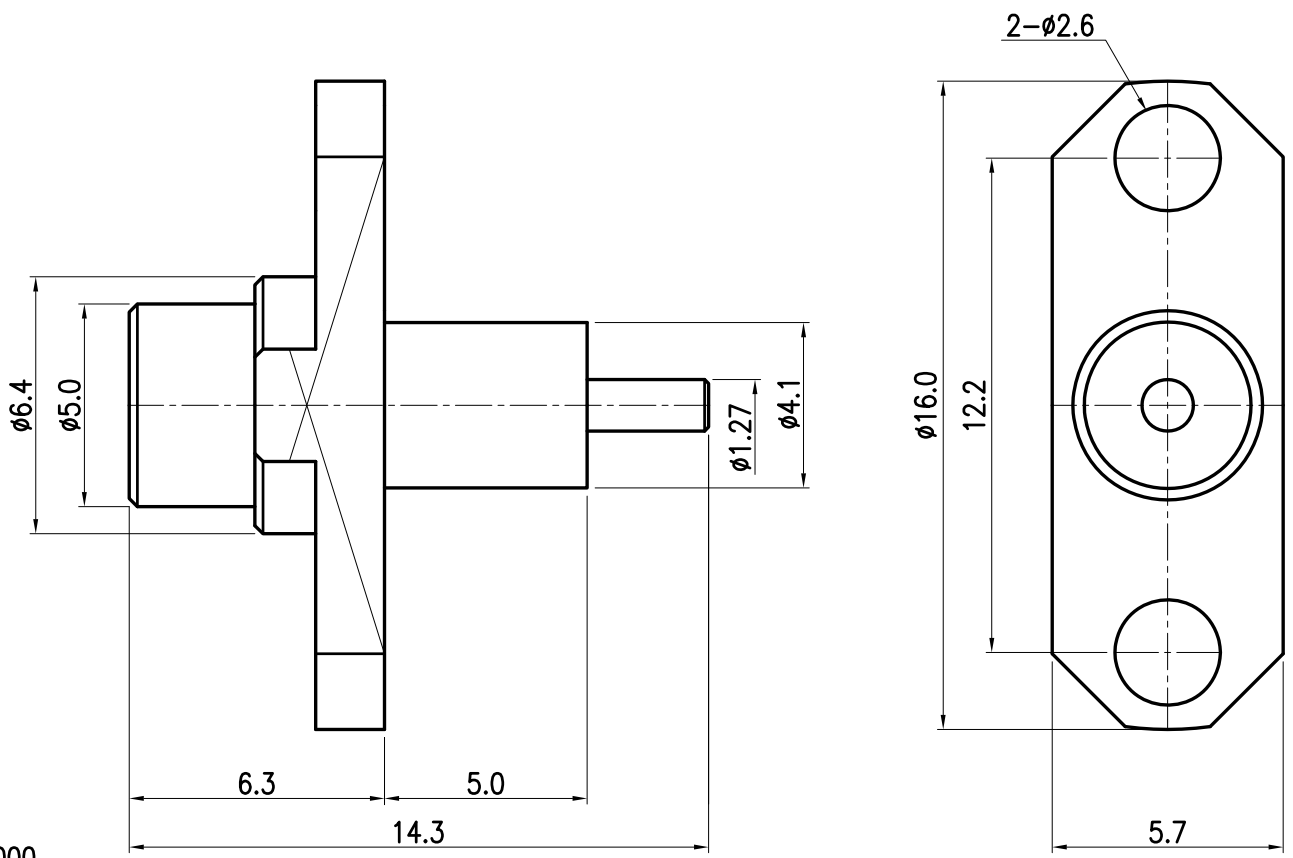


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REV	DESCRIPTION	DSG	APR	DATE



NOTE :

- Interface : CECC 22000
- Material and finish  
Center contact : Beryllium-copper / Gold  
Insulator : PTFE  
Body : Brass / Ternary-alloy
- Environmental data  
Operating Temperature : -45 ~ 120C°  
2002/95/EC (RoHS) : Compliant

UNLESS OTHERWISE SPECIFIED : ALL DIMS IN MILLIMETERS TOLERANCES ON DECIMALS 1 PLACE ±0.20 AGGLE ±1.0° 1.6σ 2 PLACE ±0.10 REMOVE BURRS, BREAK SHARP EDGES				THIRD ANGLE 		<b>Mpddevice</b> MICROWAVE PASSIVE DEVICE	
DRAW	DESIGN	CHECK	APPRO.	TITLE			
<i>GM_PARK</i>	<i>GM_PARK</i>		<i>WY_CHO</i>	MMCX JACK 2H CONNECTOR PANEL MOUNT (5.0-3.0)			
2007. 4.25	2007. 4.25		2007. 4.25	SIZE	DWG NO.	REV	
Material	SEE NOTE 2.			A4	M4005-310	A	
Finish	SEE NOTE 2.			Scale : NS	Do Not Scale Drawing	1 of 1	